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FACSIMILE COVER SHEETDATE: October 16, 2003OUR REF.: IBME-050US1TIME: 2:30 pmYOUR REF.: 10/001,421

TO:	Examiner Vu
COMPANY:	U.S. Patent & Trademark Office
FROM:	Daniel N. Calder (Reg. No. 27,424)
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OFFICE TELEPHONE:	
TITLE OF DOCUMENT:	Proposed Amendments

Total Number of Pages: 2 (Including this form)

COMMENTS

Dear Examiner Vu:

Further to our telephone conversation of today, I enclose a copy of a proposed amended claim 11. I look forward to our telephone interview on Wednesday, October 22, 2003, at 2:00 p.m.

Best regards,

Daniel N. Calder

CONFIDENTIAL AND PRIVILEGED ATTORNEY/CLIENT INFORMATION

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Appln. No.: 10/001,421
Atty. Docket No.: END919970013US2

PROPOSED AMENDMENTS

11. (Currently Amended) An interconnect structure for a semiconductor chip comprising:

- a nonreflowed solder assembly including:
 - a Pb-rich ball attached to said semiconductor chip and having an exposed surface; and
 - a thin cap layer of Sn on said exposed surface of said Pb-rich ball;
- said Sn layer ~~being sufficiently thin~~ having a thickness of less than 10.2µm (0.4 mils) and having a melting temperature lower than that of Pb so that Sn from said thin layer and Pb from said ball are uniformly diffused and intermixed after reflowing and annealing to form ~~[[an]]~~ a solder assembly ~~having a weight composition of about 97/3-Pb/Sn.~~

12.-14. (Cancelled)